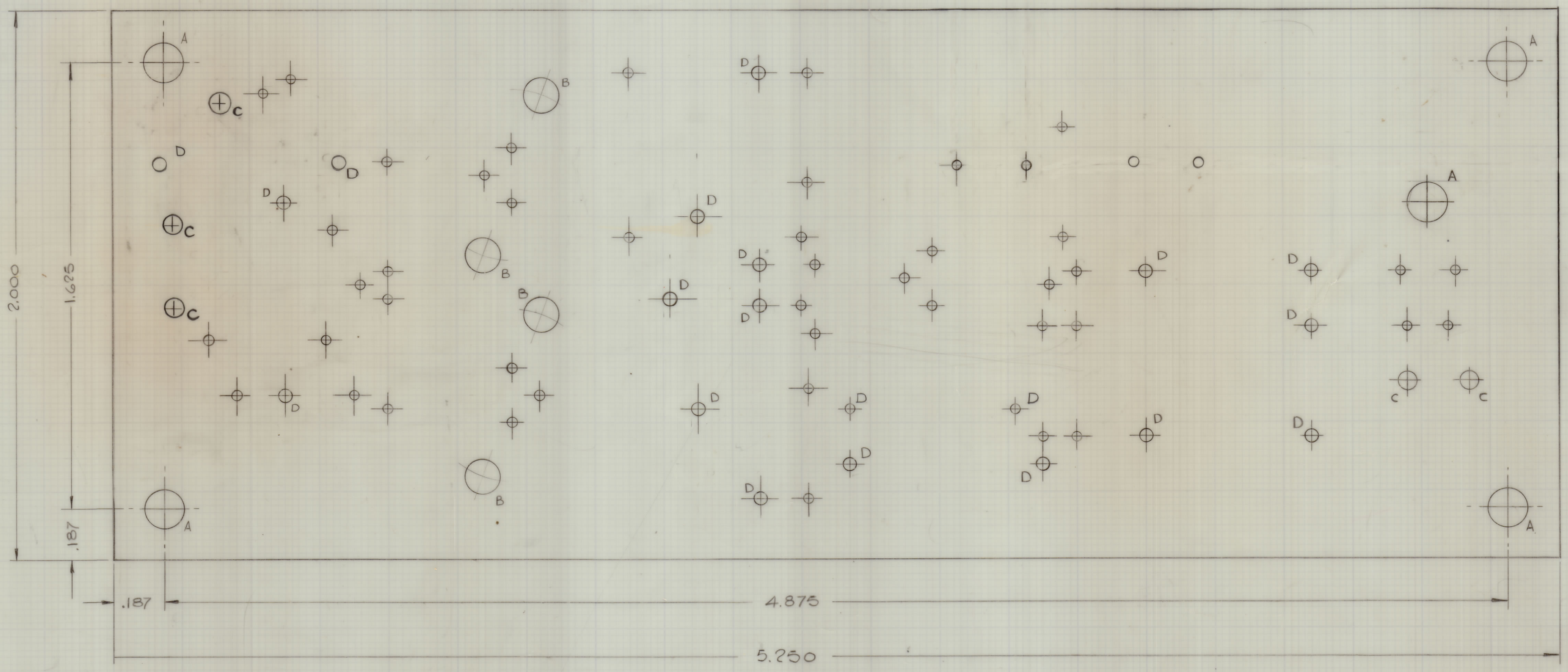


ISSUE	REV	CHANGED FROM	DATE	CH. NO.	DRAWN	CHECKER	ENR. APP.
Ø		RELEASED TO PROD	29 JAN 69		B		
A		REVISED AS PER CEMN	10 MAR 69	456	B		
B		REV AS PER CEMN	28 APR 69	473	B		
C		REV AS PER CEMN	7 FEB 71	721	BSP		
D		REV AS PER CEMN	MAR 72	742	BSP		
E		REV AS PER CEMN	MAR 72	1165	CC	4B	JYY
F		REV AS PER CEMN	15 JAN 72	1239	JMM	SOW	JAN
G		(3) C Holes Relocated	6/29/79	21886			
H		SH B RED. W/CHANGE	8.22.90		C.D.L.		

HOLE	DESCRIPTION	QTY
A	.140 DIA	5
B	.125 DIA	4
C	.063 ±.003 DIA	5
D	.046 DIA	18
UNMARKED	.035 DIA	~



BOTTOM PATTERN

3. FINISH: CONDUCTIVE PATTERN TO BE PLATED WITH A MINIMUM OF .0003 THK TIN/LEAD
2. MATERIAL: PLASTIC SHEET LAMINATED COPPER CLAD FL-GE 062-C-2/0
1. THIS BOARD MUST MEET THE REQUIREMENTS OF T.M.C SPECIFICATION 735

REFERENCE
PRINTED CIRCUIT SUB-ASSEMBLY A10735-4 (SIZE A)
TERMINAL MOUNTING

NOTES

TOLERANCES UNLESS OTHERWISE SPECIFIED	SCALE	4:1
ALL DIM .015	DRILL PUNCH COMMERCIAL STOCK	
FEEL DIM .04	RISE AND MANUFACTURERS	
ANGULAR DIM 1:0000	TOLERANCES ARE NOT INCLUDED	

MODEL	PROJECT NO.	DATE
AMC 8	074/69	17 JAN 1969

STOCK SIZE		TMC (Canada) LIMITED OTTAWA ONTARIO	
SEE NOTE 2	MATERIAL	PRINTED CIRCUIT ASSY	
SEE NOTE 2	WEIGHT PER SQ	PRE-AMPLIFIER	
TYPE & TEMPER	DRAWN	ELEC DES APP	MACH DES APP
HEAT TREAT SPEC	CHECKED	FINAL APPROVAL	
SEE NOTE 3	FINISH & SPEC NO	SHIT 2 of 8 A10735-2 H	